

# PRODUCT DATA SHEET

## SikaBond®-152

Elastic wood floor adhesive

### DESCRIPTION

SikaBond®-152 is a 1-part wood floor adhesive for all types of wood flooring and suitable for most common types of floor substrates. The adhesive is easy to apply by using SikaBond® dispensers or application guns and maintains very stable trowel peaks.

### USES

#### Full surface bonding of wood floor types:

- Engineered wood
- Mosaic parquet
- Lamparquet (≤ 55 x 220 mm, thickness ≥ 10 mm)
- Solid planks (10 x thickness > width)

#### Subfloor types:

- Concrete screed
- Cement screed
- Magnesite screed
- Calcium sulphate screed
- Parquet

- Plywood
- Chipboard (V100)
- OSB

### CHARACTERISTICS / ADVANTAGES

- Can be used with application guns and dispensers
- Can be used with Sika AcouBond® System
- Can also be trowel applied
- Very low emissions

### SUSTAINABILITY

- Conformity with LEED v4 EQc 2: Low-Emitting Materials
- VOC Emission classification GEV-EMICODE EC 1<sup>PLUS</sup>
- Class A+ according to French Regulation on VOC emissions
- VOC Emission certificate according to AgBB und DIBt approval requirements, test report No.Z-155.10-498

### PRODUCT INFORMATION

Composition	Silane terminated polymer
Packaging	17 kg container
	Refer to current price list for packaging variations.
Shelf life	12 months from the date of production
Storage conditions	The product must be stored in original, unopened and undamaged sealed packaging in dry conditions at temperatures between +5 °C and +25 °C. Always refer to packaging.
Colour	Parquet brown
Density	~1,65 kg/l (ISO 1183-1)

## TECHNICAL INFORMATION

Shear strength	Elastic adhesive	(ISO 17178)
Service temperature	+5 °C min. / +40 °C max.	

## APPLICATION INFORMATION

Consumption	<b>Full surface bonding - SikaBond® Dispensers:</b> Refer to the Method Statement: SikaBond® Dispenser series.	
	<b>Sika® AcouBond®-System:</b> 400–500 ml/m <sup>2</sup> for SikaLayer®-03 and 500–600 ml/m <sup>2</sup> for SikaLayer®-05. All cut-outs must be filled. Use a triangular nozzle with an 8 × 10 mm opening.	
	<b>Beaded bonding - Application gun:</b> 330–500 g/m <sup>2</sup> (44 ml per running metre), depending on bead spacing (solid wood boards, 3-ply engineered wood, chipboards).	
	<b>Full surface bonding - Trowel:</b>	
	<b>Consumption</b>	<b>V-notched trowel type (TKB Germany)</b>
	800–1000 g/m <sup>2</sup>	Trowel B3
	900–1200 g/m <sup>2</sup>	Trowel B6
	1000–1300 g/m <sup>2</sup>	Trowel B11 / P5
	When bonding long or wide boards or applying on uneven substrates a sufficient amount of adhesive must be applied to provide full surface bonding. Substrates primed with Sika® Primer MR Fast or Sika® Primer MB, may reduce the consumption.	
Sag flow	SikaBond®-152 flows well from SikaBond® Dispensers or application guns while maintaining stable peaks.	
Ambient air temperature	+15 °C min. / +35 °C max.	
Relative air humidity	40 % min. / 70 % max.	
Substrate temperature	+15 °C min. / +35 °C max. (+20 °C min. / +35 °C max with underfloor heating). Temperatures should be maintained during application and until fully cured.	
Curing time	Walkable	~8 hours
	Sandable	~12 hours
	Fully cured	~48–72 hours
	Curing times depend on environmental and subfloor conditions, adhesive layer thickness and wood flooring type. The above curing times were determined at +23 °C / 50 % r.h.	
Skin time / laying Time	~30 minutes (23 °C / 50 % r.h.)	

## BASIS OF PRODUCT DATA

All technical data stated in this Product Data Sheet are based on laboratory tests. Actual measured data may vary due to circumstances beyond our control.

## FURTHER INFORMATION

- Pre-treatment Sealing and Bonding Chart
- Method Statement: SikaBond® Dispenser series
- Method Statement: Sika® AcouBond®-System and cordon / beaded application
- Method Statement: Full Surface Bonding

## IMPORTANT CONSIDERATIONS

- Substrate moisture content measurements alone are not a sufficient basis for the wood flooring installer to decide on readiness for covering. Other tests must be considered as mentioned for existing cementitious sub-floors and new screeds. Tests must be appropriate to the type of floor covering, composition, behaviour of existing sub-floor, new screed and job site ambient conditions.
- The surface of the substrate must meet the strength requirements of the wood flooring manufacturer. Testing the tensile strength of the substrate alone is not sufficient to assess the surface condition. Addi-

tional criteria such as roughness, absorbency and cleanliness must also be evaluated. For wood floor bonding, a minimal tensile strength of  $\geq 1 \text{ N/mm}^2$  is required (according to EN 13892-8). New mastic asphalt (fully broadcasted) must meet the requirements of IC 10 or IC 15 (DIN 18 354 and DIN 18 560). Old mastic asphalt must in every case be tested in several floor locations and evaluated by a specialist laboratory.

- If there is any doubt the floor substrate cannot satisfy the moisture or surface conditions, the installation must not progress. Alternative floor products that can improve the substrate conditions should be considered such as surface hardeners or thin layer overlays. Contact Sika Technical Services for additional information.
- Reference must be made to the wood flooring manufacturer's installation instructions and recommendations.
- For optimum workability, the recommended adhesive temperature is  $\geq +15 \text{ }^\circ\text{C}$ .
- Be aware of jobsite relative air humidity conditions.
- A preliminary adhesion test must be carried out before any application onto glazed tiles.
- Wood floors chemically pre-treated (e.g. those produced or treated with ammonia, wood stain, timber preservative) and woods with a relatively high oil content. Written agreement from Sika Technical Services must be obtained before using SikaBond®-152.
- Do not use on polyethylene (PE), polypropylene (PP), polytetrafluoroethylene (PTFE / Teflon), and other similar plasticized synthetic materials.
- Incompatible floor primers can negatively influence the adhesion of SikaBond®-152. Pre-trials must be carried out before using for full application.
- When laying wood flooring without tongue and grooved joints, e.g. mosaic parquet floors. Avoid the adhesive extruding into the joints between the wood pieces.
- Avoid contact between any wood floor surface sealer coating and adhesive. If direct contact with the adhesive is unavoidable, then compatibility must be checked and confirmed before the use of any coatings. Contact Sika Technical Services for additional information.
- Do not expose uncured SikaBond®-152 to alcohol containing products as they may interfere with the curing reaction.

## ECOLOGY, HEALTH AND SAFETY

For information and advice on the safe handling, storage and disposal of chemical products, users shall refer to the most recent Safety Data Sheet (SDS) containing physical, ecological, toxicological and other safety-related data.

## APPLICATION INSTRUCTIONS

### SUBSTRATE PREPARATION

#### General

The substrate must be sound, clean, dry and free of all contaminants such as dirt, oil, grease, cement laitance, wax, varnish, old adhesive residue and poorly bonded

paint coatings which could affect adhesion.

All dust, loose and friable material must be completely removed from all surfaces before the application of SikaBond®-152, preferably by vacuum extraction equipment.

#### Concrete / cementitious screeds

Substrate must be ground flat to provide a smooth surface without any irregularities. Fill any voids or cavities with appropriate Sika® compatible flooring repair or levelling products.

#### Calcium sulphate (Anhydrite) screeds

Substrate must be ground flat to provide a smooth surface without any irregularities. Fill any voids or cavities with appropriate Sika® compatible flooring repair or levelling products.

#### Mastic asphalt

Prime with Sika® Primer MR Fast or Sika® Primer MB and broadcast with quartz sand. Refer to individual Product Data Sheets.

#### Glazed ceramic and old existing ceramic tiles

Degrease and clean with Sika® Aktivator-205. Alternatively tile surfaces must be ground to remove the glaze.

#### Wood

Wood types such as chipboards (V100), OSB or plywood as well as gypsum boards must be securely fixed to the substructure. Remove any surface irregularities using appropriate equipment. For floating dry-floors, contact Sika Technical Services for additional information.

#### Other substrate types

Contact Sika Technical Services.

#### Priming

SikaBond®-152 can be used without priming on concrete / cementitious/ anhydrite screeds, chipboards, concrete and ceramic tiles.

For broadcasted mastic asphalt, concrete / cementitious subfloors or screeds with excessive moisture content, old adhesive residue or weak substrates, Sika® Primer MB must be used. Refer to individual Product Data Sheet or contact Sika Technical Services for additional information.

Before wood floors may be installed in non-insulated areas, such as basements or other areas without a damp proof membrane, Sikafloor®EpoCem must be applied and sealed with Sika®Primer MB to control the moisture. Contact Sika Technical Services for additional information.

### APPLICATION METHOD / TOOLS

Reference must be made to further documentation where applicable, such as relevant method statement, application manual and installation or working instructions.

#### Existing sub-floors

Sub-floor has to be ready for covering at time of installation of the wood flooring to prevent adhesive adhesion failure. It is the responsibility of the wood flooring installer to confirm the sub-floor is acceptable for laying the specific type of wood flooring. The installation area's ambient conditions must also be taken into consideration with regard to the effect on the sub-floor and wood flooring. Sub-floor and timber moisture content readings together with the installation area's air humidity conditions must be satisfied

before the wood flooring installation.

### New screeds

Screeds have to be ready for covering at time of installation of the wood flooring to prevent adhesive adhesion failure. It is the responsibility of the wood flooring installer to confirm the screed is acceptable for laying the specific type of wood flooring. The installation area's ambient conditions must also be taken into consideration with regard to the effect on the new screed and wood flooring. New screed and timber moisture content readings together with the installation area's air humidity conditions must be satisfied before the wood flooring installation. Acceptability must also be confirmed after consultation with the customer and if necessary also with the assistance of the screed installer.

### Wood flooring conditioning

The wood flooring must be conditioned in the area where it is to be installed in accordance with the manufacturer's recommendations.

### SikaBond® Dispenser application – Full surface bond

SikaBond®-152 is applied to the prepared substrate directly from the SikaBond® Dispenser.

### Sika® AcouBond®-System application

Refer to Method Statement: Sika® AcouBond®-System and cordon / beaded application or contact Sika Technical Services.

### Application gun – Beaded bond

After inserting product into the gun, extrude a triangular shaped bead of adhesive approximately 10 mm high and 8 mm wide (depending on the wood floor type) on the prepared subfloor. The distance between beads must not exceed 150 mm

### Trowel application – Full surface bond

Onto the prepared substrate, spread SikaBond®-152 uniformly with a v-notched trowel or spreader comb directly from the product container.

### Laying wood flooring

Refer to wood flooring manufacturer's recommendations for expansion gap locations and dimensions. Press the wood floor pieces firmly into the adhesive so the wood floor underside is completely covered with the adhesive. The pieces can then be adjusted into position using a rubber hammer and an impact block.

### Cleaning

Fresh, uncured adhesive on the wood floor surface must be removed immediately with a clean cloth and if necessary also cleaned with Sika® Remover-208. Always test wood floor surfaces for compatibility with Sika® Remover-208 before use.

Reference must also be made to the wood flooring manufacturers cleaning recommendations.

### Sanding and finishing

The floor shall not be walked on earlier than 8 hours and not sanded or mechanically polished earlier than

12 hours after installation. Refer to curing times.

### CLEANING OF EQUIPMENT

Clean all tools and application equipment immediately after use with Sika® Remover-208. Once cured, hardened material can only be removed mechanically. For cleaning skin use Sika® Cleaning Wipes-100.

### LOCAL RESTRICTIONS

Please note that as a result of specific local regulations the performance of this product may vary from country to country. Please consult the local Product Data Sheet for the exact description of the application fields.

### LEGAL NOTES

The information, and, in particular, the recommendations relating to the application and end-use of Sika products, are given in good faith based on Sika's current knowledge and experience of the products when properly stored, handled and applied under normal conditions in accordance with Sika's recommendations. In practice, the differences in materials, substrates and actual site conditions are such that no warranty in respect of merchantability or of fitness for a particular purpose, nor any liability arising out of any legal relationship whatsoever, can be inferred either from this information, or from any written recommendations, or from any other advice offered. The user of the product must test the product's suitability for the intended application and purpose. Sika reserves the right to change the properties of its products. The proprietary rights of third parties must be observed. All orders are accepted subject to our current terms of sale and delivery. Users must always refer to the most recent issue of the local Product Data Sheet for the product concerned, copies of which will be supplied on request.

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#### Product Data Sheet

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